

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	20	(US-20010029283-\$ or US-20010026847-\$ or US-20010010840-\$ or US-20010027926-\$ or US-20020118027-\$).did. or (US-6451381-\$ or US-6447846-\$ or US-6650387-\$ or US-5723345-\$ or US-5082789-\$ or US-4510436-\$ or US-4728882-\$ or US-5337018-\$ or US-5106462-\$ or US-6296949-\$ or US-6004494-\$).did. or (WO-9509361-\$).did. or (JP-62182643-\$).did. or (JP-04350550-\$ or WO-9957548-\$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 17:51
L4	1	photoresist and mask and L3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 17:51
S1	1	"10529709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/09 13:28
S2	39	((TOSHI AKI) near2 (KAWANISHI)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/09 13:38
S4	42	((KI YOSHI) near2 (YAMAGI SHI)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/09 13:38
S5	265	((KI YOSHI) near2 (YAMAGI SHI)).INV.	EPO; JPO; DERWENT	OR	ON	2008/09/09 13:38
S6	29	((TAKAYUKI) near2 (TAKAHATA)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/09 13:38
S9	874	"422/82.01".CCLS.	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/09 13:38
S10	70	"422/82.01".CCLS.	EPO; JPO; DERWENT	OR	ON	2008/09/09 13:38
S11	796	204/403.01.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 08:43
S12	0	204/400+.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 08:43
S13	1322	204/400.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 08:43
S14	734	204/409.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 08:44
S15	0	"324".ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 08:44

S16	116	73/61.61.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 08:44
S17	2741	S11 S13 S14 S16	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 08:45
S18	1	"4510436".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 09:00
S19	1	"4728882".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 09:00
S20	1	"5060619".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 09:06
S21	1	"5337018".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 09:06
S22	0	jp4350550	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 10:19
S23	6	"4350550"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 10:19
S24	44	"350550"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 10:20
S25	73	"350550"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/09 10:20
S26	7	"4350550"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/09 10:22
S27	71	((TAKAYUKI) near2 (TAKAHATA)).INV.	EPO; JPO; DERWENT	OR	ON	2008/12/09 10:25
S28	1	jp2004350550	EPO; JPO; DERWENT	OR	ON	2008/12/09 10:26
S29	2	"2004350550"	EPO; JPO; DERWENT	OR	ON	2008/12/09 10:26
S30	2	"04350550"	EPO; JPO; DERWENT	OR	ON	2008/12/09 10:33
S31	1	"62182643"	EPO; JPO; DERWENT	OR	ON	2008/12/09 10:56
S32	5	"9509361"	EPO; JPO; DERWENT	OR	ON	2008/12/09 11:04
S33	3	"9957548"	EPO; JPO; DERWENT	OR	ON	2008/12/09 11:08
S34	941791	concentrat\$5 or percent\$6 or saturat\$4 or ppm or ppb	EPO; JPO; DERWENT	OR	ON	2008/12/09 11:17
S35	9110	(alcohol or ethanol or etoh or ethyl\$1alcohol or ethyl adj alcohol or "ch.sub3. sub2oh" or ch3ch2oh) with (detect\$4 or sensing or sensor or monitor\$3 or measure\$4 or analy\$4)	EPO; JPO; DERWENT	OR	ON	2008/12/09 11:21

S36	235754	pcb or printed near2 circuit \$3 or wiring near3 pattern or ix or intergrat\$3 near3 circuit\$3 or comb near3 (tooth or teeth)	EPO; JPO; DERWENT	OR	ON	2008/12/09 11:24
S37	705257	(foil or metal\$4 or alumni \$5 or coper or conductive or pt or platihum or nicket or titanium or ni or cu or al or ti) near5 (layer or film or lamina\$5)	EPO; JPO; DERWENT	OR	ON	2008/12/09 11:28
S38	384403	(resin or polymer or polyimide or kapton or Norton adj th or kaptrex or epox\$4 or \$5urethan\$3) with (coat\$3 or over\$1coat \$3 or protect\$5 or enrob \$3)	EPO; JPO; DERWENT	OR	ON	2008/12/09 11:33
S40	0	S34 S35 S36 S37 S38	EPO; JPO; DERWENT	AND	ON	2008/12/09 11:46
S41	667	inductive adj capacity	EPO; JPO; DERWENT	OR	ON	2008/12/09 12:17
S42	632	specific inductive capacity	EPO; JPO; DERWENT	ADJ	ON	2008/12/09 12:17
S43	1516	specific inductive capacity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:18
S44	182	alcohol concentration detect \$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:18
S45	217951	photoresist	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:19
S46	83524	metal foil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:19
S47	24568	metallic foil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:19
S48	103652	S46 or S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:19

S49	58457	oscillation frequency	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:19
S50	2047159	electrodes	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:19
S51	56603	wiring pattern	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:20
S52	3	S43 S44 S45 S49 S50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/09 12:20
S53	0	123/406.12.ccls	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/09 12:23
S54	0	123/406.ccls	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/09 12:23
S55	0	73/61.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/09 12:24
S56	96	73/61.46.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/09 12:24
S57	0	123/406.12.ccls	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/09 12:25
S58	162	S43 and alcohol	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:25
S59	796	204/403.01.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:26
S60	1322	204/400.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:26

S61	734	204/409.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:26
S62	116	73/61.61.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:26
S63	2741	S59 S60 S61 S62	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:26
S64	2834	S63 or S56	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:26
S65	3	S64 and S58	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:27
S66	1778	inductive capacity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:27
S67	191	alcohol and S66	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:28
S68	1	S63 and S67	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:31
S69	278001	chemical adj vapor adj deposition or cvd	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:33
S70	298912	sputter\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:34
S71	471211	S69 or S70	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:34
S72	4	S71 and S44	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/09 12:34

S73	162	specific adj inductive adj capacity and alcohol	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/09 12:39
S74	1	"10529709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/09 12:44
S75	39	((TOSHI AKI) near2 (KAWANISHI)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:44
S76	198	((TOSHI AKI) near2 (KAWANISHI)).INV.	EPO; JPO; DERWENT	OR	ON	2008/12/09 12:44
S77	42	((KI YOSHI) near2 (YAMAGI SHI)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:44
S78	265	((KI YOSHI) near2 (YAMAGI SHI)).INV.	EPO; JPO; DERWENT	OR	ON	2008/12/09 12:44
S79	30	((TAKAYUKI) near2 (TAKAHATA)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:44
S80	30	((TAKAYUKI) near2 (TAKAHATA)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:44
S81	70	S74 or S75 or S76 or S77 or S78 or S79 or S80	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:44
S82	3	S73 and S81	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/09 12:45
S83	162	specific adj inductive adj capacity and alcohol	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/09 12:45
S84	0	wooo17636	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/09 13:03
S85	3	"0017636"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/09 13:03
S86	87299	acrylic with resin	EPO; JPO; DERWENT	OR	ON	2008/12/12 12:01
S87	326384	sputt\$6 or etching	EPO; JPO; DERWENT	OR	ON	2008/12/12 12:01
S88	1221058	electrode	EPO; JPO; DERWENT	OR	ON	2008/12/12 12:01
S89	10	S86 S87 S88	EPO; JPO; DERWENT	WITH	ON	2008/12/12 12:01

S90	216857	acrylic with resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:02
S91	810980	sputt\$6 or etching	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:02
S92	2047897	electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:02
S93	1241357	alcohol	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:03
S94	1	S90 S91 S92 S93	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2008/12/12 12:03
S95	208873	acrylic with resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:05
S96	769005	sputtering or etching	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:05
S97	1915839	electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:05
S98	1086185	alcohol	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:06
S99	6745	S95 S96 S97 S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/12 12:07
S101	44	S95 S96 S97 S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2008/12/12 12:08
S102	942	"422/82.01".CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:09

S103	786	204/403.01.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:10
S104	1511	204/400.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:10
S105	621	204/409.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:10
S106	108	73/61.61.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:11
S107	0	123/406.12.ccls	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:12
S108	87	73/61.46.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:12
S112	178	436/132.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:14
S113	299	422/84.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:14
S114	0	250/339.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:14
S115	0	73/23.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:15
S116	0	73/23.2ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:17
S117	1566	73/23.2.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:17
S118	293	73/23.3.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:18



S119	1106	73/23.31.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:18
S120	477	73/23.32.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:18
S121	7143	S102 S103 S104 S105 S106 S108 S112 S113 S117 S118 S119 S120	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/12 12:20
S122	30	S99 S121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/12 12:21
S123	30	S98 and S122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/12 12:21
S124	8	"113" and S122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/12 12:21
S125	178	436/132.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:31
S126	0	capacitance and S125	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:35
S127	23	electrode and S125	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:35
S128	2	resin and S127	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:36
S129	1	sputtering and S125	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:39
S130	183630	chemical adj vapor adj deposition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:41
S131	1	S130 and S125	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:41

S132	76	ethanol and S125	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:43
S133	10	gasoline and S125	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:43
S134	9	S132 and S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:45
S135	2	resin and S134	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 12:47
S136	4786500	resin film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:07
S137	56494	wiring adj pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:07
S138	100352	resin adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:07
S139	33773	S136 and S137	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:08
S140	102728	resin adj film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:09
S141	2050043	electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:09
S142	22216	S140 and S141	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:09
S143	5198	alcohol and S142	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:09

S144	250	comb and S143	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:10
S145	3505056	foil or film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:10
S146	250	S145 and S144	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:11
S147	12612	inductive adj capacit\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:12
S148	3	S146 and S147	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:14
S149	10625	ll and capacitance	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:15
S150	35	S146 and capacitance	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:15
S151	2478925	electrode or anode or cathode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:16
S152	674	S151 and "I35"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:16
S153	35	S151 and S150	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:17
S154	636208	resin and "35"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:18

S155	583	resin and "I35"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:18
S156	401	resin and "I29"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:18
S157	35	S153 and resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 13:19
S158	625140	thin adj film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 14:34
S159	19325133	jp 09-503062	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 16:38
S160	1	"09503062"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 16:40
S161	30	((TAKAYUKI) near2 (TAKAHATA)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/15 16:47
S162	198	((TOSHI AKI) near2 (KAWANISHI)).INV.	EPO; JPO; DERWENT	OR	ON	2008/12/15 16:47
S163	1	"jp 09503062"	EPO; JPO; DERWENT	OR	ON	2008/12/15 16:48
S164	1	"jp 2002513930"	EPO; JPO; DERWENT	OR	ON	2008/12/15 16:49
S165	1694411	"6513364" B1	EPO; JPO; DERWENT	OR	ON	2008/12/15 16:50
S166	2	("6513364").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/15 16:50
S167	0	"09674190"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 16:51

S168	0	"09674190".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 16:51
S169	3	hydrogen adj sensor and jonda	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/15 16:56
S170	0	jp2002513930	EPO; JPO; DERWENT	OR	ON	2008/12/16 06:22
S171	0	jp2002513930	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 06:23
S172	1	"2002513930"	EPO; JPO; DERWENT	OR	ON	2008/12/16 06:23
S173	31724	kapton or apical	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 07:01
S174	34454	kapton or apical or polyimide adj resin adj film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 07:02
S175	46317	copper adj foil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 07:03
S176	1587970	alcohol or ethanol or methanol	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 07:03
S177	1650866	S174 S175 S176	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 07:03
S178	408	S174 S175 S176	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:04
S179	438982	chemical adj vapor adj deposition or cvd or sputtering	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:04

S180	181	S178 S179	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:05
S181	1546546	conductivity or conductance or conducting	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:06
S182	114	S180 and S181	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:06
S183	183211	comb or interdigitated	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:07
S184	13	S183 and S182	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:07
S185	292375	sio2 or silicon adj dioxide or al2oc	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:28
S186	324181	sio2 or silicon adj dioxide or al2o3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:28
S187	19	S180 and S186	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:29
S188	4334970	sensor or sensing or detector or detecting	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:30
S189	4	S187 and S188	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:30
S190	289	S174 S175 S179 S181	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:32

S191	10812	S176 with S188	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:32
S192	350	nd S191	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:33
S193	4	S190 S191	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 07:33
S194	0	("2006/0042940").URPN.	USPAT	OR	ON	2008/12/16 07:34
S195	1783	inductive adj capacity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 08:07
S196	3	S174 S175 S176 S179 S195	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 08:10
S197	2008879	capacitance or capacity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 08:11
S198	67370	S176 S197 S188	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 08:12
S199	21480	S179 and foil	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 08:12
S200	1037	S198 and S199	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 08:13
S201	923	S200 and film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 08:13

S202	31011819	@pd<"20020930"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 08:17
S203	199	S201 and S202	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 08:18
S204	10812	S176 with S188	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 08:19
S205	5	S203 and S204	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/16 08:19
S206	20	(US-20010029283-\$ or US-20010026847-\$ or US-20010010840-\$ or US-20010027926-\$ or US-20020118027-\$).did. or (US-6451381-\$ or US-6447846-\$ or US-6650387-\$ or US-5723345-\$ or US-5082789-\$ or US-4510436-\$ or US-4728882-\$ or US-5337018-\$ or US-5106462-\$ or US-6296949-\$ or US-6004494-\$).did. or (WO-9509361-\$).did. or (JP-62182643-\$).did. or (JP-04350550-\$ or WO-9957548-\$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 08:21
S207	4	S206 and (stuck or tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 09:18
S208	4	S206 and foil	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 09:31
S209	3	S206 and comb	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 09:48
S210	6	S206 and (comb or interdigitated)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 09:51
S211	5	S195 and S206	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 10:05



S212	20	(US-20010029283-\$ or US-20010026847-\$ or US-20010010840-\$ or US-20010027926-\$ or US-20020118027-\$).did. or (US-6451381-\$ or US-6447846-\$ or US-6650387-\$ or US-5723345-\$ or US-5082789-\$ or US-4510436-\$ or US-4728882-\$ or US-5337018-\$ or US-5106462-\$ or US-6296949-\$ or US-6004494-\$).did. or (WO-9509361-\$).did. or (JP-62182643-\$).did. or (JP-04350550-\$ or WO-9957548-\$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:10
S213	11	S212 and sputtering	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:10
S214	277410	chemical adj vapor adj deposition or cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:47
S215	5	S214 and S212	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:47
S216	5	S212 and S215	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:48
S217	2	copper and S216	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:49
S218	3	alcohol and S216	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:50
S219	1	(gasoline or fuel) and S218	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 11:50
S220	3	S212 S213 S214 S218	US-PGPUB; USPAT; EPO; JPO; DERWENT	AND	ON	2008/12/16 11:59
S221	6	etching and sputtering and S212	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:17
S222	425387	aluminum adj oxide or al2o3 or silicon adj dioxide or sio2	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:22
S223	2221	S214 near S222	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:23
S224	0	S223 and S212	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:23

S225	8176584	top adj coat or insulat\$4 or top or layer	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:24
S226	2087	S225 and "I20"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:24
S227	2087	S225 and "I20"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:25
S228	20	S212 and S225	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:25
S229	6	S222 and S228	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 12:25
S230	630543	comb or tooth or interdigitated	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 13:00
S231	6	S230 and S212	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 13:00
S232	2	"6513364"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 13:10
S233	7	(US-20020118027-\$).did. or (US-6513364-\$ or US-6296949-\$).did. or (WO-9509361-\$).did. or (JP-62182643-\$).did. or (WO-9957548-\$ or JP-04350550-\$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 14:18
S234	1	S233 and photoresist	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 14:18
S235	5	(stick or stuck or tape or foil or adhere) and S212	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 14:28
S236	1	photoresist and etch and S212	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 14:30
S237	10185	anodization	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 14:35
S238	1	S212 and S237	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 14:35
S239	4	S212 and mask	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 14:41
S240	10703	(comb or tooth or interdigitated) and "I1"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 15:59

S241	20	(US-20010029283-\$ or US-20010026847-\$ or US-20010010840-\$ or US-20010027926-\$ or US-20020118027-\$).did. or (US-6451381-\$ or US-6447846-\$ or US-6650387-\$ or US-5723345-\$ or US-5082789-\$ or US-4510436-\$ or US-4728882-\$ or US-5337018-\$ or US-5106462-\$ or US-6296949-\$ or US-6004494-\$).did. or (WO-9509361-\$).did. or (JP-62182643-\$).did. or (JP-04350550-\$ or WO-9957548-\$).did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 16:09
S242	630543	comb or tooth or interdigitated	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 16:09
S243	6	S241 and S242	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/12/16 16:09
S244	4	(sio2 or silicon adj dioxide or al2o3) and S241	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/12/16 16:19

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